

ON Semiconductor				10/15/2019
Base Part		MJD44H11T	HF	
Orderable Part		MJD44H11TM	Total weight (mg)	291.831
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	5.93	Silicon (Si)	7440-21-3	100
Die Attach Solder	2.353	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	150.208	Tin (Sn)	7440-31-5	0.10651896
		Nickel (Ni)	7440-02-0	0.03195569
		Copper (Cu)	7440-50-8	99.86152535
Mold Compound-Black	129	Ortho Cresol Novolac Resin	29690-82-2	20
		Carbon Black (C)	1333-86-4	1
		Fused Silica (SiO2)	60676-86-0	79
Plating	1.9	Tin (Sn)	7440-31-5	100
Wire Bond - Al	2.44	Aluminum (Al)	7429-90-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				